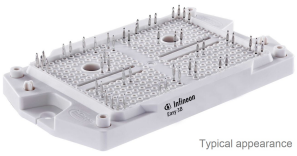
EasyPACK™ module with TRENCHSTOP™ IGBT7 and CoolSiC™ Schottky diode and PressFIT / NTC

Features


Typical appearance

- Electrical features
  - V_{CES} = 950 V
  - $I_{C\ nom}$ = 200 A / I_{CRM} = 300 A
  - CoolSiC™ Schottky diode gen 5
  - Low switching losses
  - TRENCHSTOP™ IGBT7
- Mechanical features
  - Integrated NTC temperature sensor
  - Al_2O_3 substrate with low thermal resistance
  - PressFIT contact technology
  - Compact design

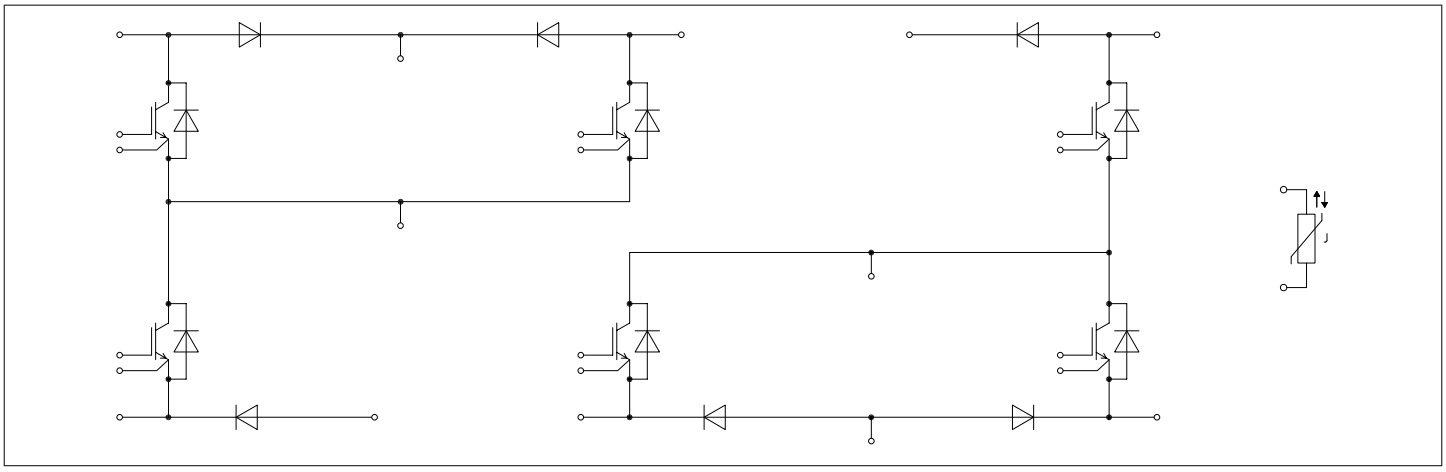
Potential applications

- Three-level applications
- Solar applications
- UPS systems

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description



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1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, f = 50 Hz, *t* = 1 min	3.2	kV
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	d_{Creep}	terminal to heatsink	11.2	mm
Creepage distance	d_{Creep}	terminal to terminal	6.8	mm
Clearance	d_{Clear}	terminal to heatsink	9.4	mm
Clearance	d_{Clear}	terminal to terminal	5.5	mm
Comparative tracking index	*CTI*		> 400	
Relative thermal index (electrical)	*RTI*	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Stray inductance module	L_{sCE}				18		nH
Storage temperature	T_{stg}			-40		125	°C
Mounting torque for module mounting	*M*	- Mounting according to valid application note	M5, Screw	1.3		1.5	Nm
Weight	*G*				78		g

Note: The current under continuous operation is limited to 25A rms per connector pin.

2 IGBT, Boost

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Collector-emitter voltage	V_{CES}		T_{vj} = 25 °C	950	V
Implemented collector current	I_{CN}			200	A
Continuous DC collector current	I_{CDC}	$T_{vj\,max}$ = 175 °C	T_H = 65 °C	120	A
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\,op}$		300	A
Gate-emitter peak voltage	V_{GES}			±20	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\,sat}$	I_C = 45 A, V_{GE} = 15 V	T_{vj} = 25 °C		1.23	1.48	V
			T_{vj} = 125 °C		1.27		
			T_{vj} = 150 °C		1.27		
Gate threshold voltage	V_{GEth}	I_C = 3.25 mA, V_{CE} = V_{GE}, T_{vj} = 25 °C		4.35	5.10	5.85	V
Gate charge	Q_G	V_{GE} = ±15 V, V_{CC} = 600 V			0.45		µC
Internal gate resistor	R_{Gint}	T_{vj} = 25 °C			1.5		Ω
Input capacitance	C_{ies}	f = 100 kHz, T_{vj} = 25 °C, V_{CE} = 25 V, V_{GE} = 0 V			12.6		nF
Reverse transfer capacitance	C_{res}	f = 100 kHz, T_{vj} = 25 °C, V_{CE} = 25 V, V_{GE} = 0 V			0.039		nF
Collector-emitter cut-off current	I_{CES}	V_{CE} = 950 V, V_{GE} = 0 V	T_{vj} = 25 °C			0.026	mA
Gate-emitter leakage current	I_{GES}	V_{CE} = 0 V, V_{GE} = 20 V, T_{vj} = 25 °C				100	nA
Turn-on delay time (inductive load)	t_{don}	I_C = 45 A, V_{CC} = 500 V, V_{GE} = ±15 V, R_{Gon} = 3.9 Ω	T_{vj} = 25 °C		0.068		µs
			T_{vj} = 125 °C		0.078		
			T_{vj} = 150 °C		0.080		
Rise time (inductive load)	t_r	I_C = 45 A, V_{CC} = 500 V, V_{GE} = ±15 V, R_{Gon} = 3.9 Ω	T_{vj} = 25 °C		0.007		µs
			T_{vj} = 125 °C		0.008		
			T_{vj} = 150 °C		0.009		
Turn-off delay time (inductive load)	t_{doff}	I_C = 45 A, V_{CC} = 500 V, V_{GE} = ±15 V, R_{Goff} = 1.5 Ω	T_{vj} = 25 °C		0.198		µs
			T_{vj} = 125 °C		0.263		
			T_{vj} = 150 °C		0.280		
Fall time (inductive load)	t_f	I_C = 45 A, V_{CC} = 500 V, V_{GE} = ±15 V, R_{Goff} = 1.5 Ω	T_{vj} = 25 °C		0.043		µs
			T_{vj} = 125 °C		0.089		
			T_{vj} = 150 °C		0.097		
Turn-on energy loss per pulse	E_{on}	I_C = 45 A, V_{CC} = 500 V, L_σ = 35 nH, V_{GE} = ±15 V, R_{Gon} = 3.9 Ω, di/dt = 4000 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		0.473		mJ
			T_{vj} = 125 °C		0.544		
			T_{vj} = 150 °C		0.557		
Turn-off energy loss per pulse	E_{off}	I_C = 45 A, V_{CC} = 500 V, L_σ = 35 nH, V_{GE} = ±15 V, R_{Goff} = 1.5 Ω, dv/dt = 3200 V/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		1.14		mJ
			T_{vj} = 125 °C		1.95		
			T_{vj} = 150 °C		2.19		
Thermal resistance, junction to heat sink	R_{thJH}	per IGBT, λ_{grease} = 3.3 W/(m·K)			0.433		K/W

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Temperature under switching conditions	$T_{vj\,op}$		-40		150	°C

3 Diode, Reverse

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Repetitive peak reverse voltage	V_{RRM}		T_{vj} = 25 °C	1200	V
Continuous DC forward current	I_F			75	A
Repetitive peak forward current	I_{FRM}	t_P = 1 ms		150	A
I^2t - value	I^2t	t_P = 10 ms, V_R = 0 V	T_{vj} = 125 °C	453	A^2s
			T_{vj} = 175 °C	392	

Table 6 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Forward voltage	V_F	I_F = 75 A, V_{GE} = 0 V	T_{vj} = 25 °C		1.72	2.10	V
			T_{vj} = 125 °C		1.59		
			T_{vj} = 175 °C		1.52		
Thermal resistance, junction to heat sink	R_{thJH}	per diode, λ_{grease} = 3.3 W/(m·K)			0.933		K/W
Temperature under switching conditions	$T_{vj\,op}$			-40		175	°C

Note: $T_{vj\,op}$ > 150°C is allowed for operation at overload conditions. For detailed specifications, please refer to AN 2018-14.

4 Diode, Boost

Table 7 Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Repetitive peak reverse voltage	V_{RRM}		T_{vj} = 25 °C	1200	V

(table continues...)

Table 7 (continued) Maximum rated values

Parameter	Symbol	Note or test condition		Values	Unit
Continuous DC forward current	I_F			60	A
Repetitive peak forward current	I_{FRM}	t_P = 1 ms		120	A
I^2t - value	I^2t	t_P = 10 ms, V_R = 0 V	T_{vj} = 125 °C	472	A^2s
			T_{vj} = 150 °C	450	

Table 8 Characteristic values

Parameter	Symbol	Note or test condition		Values			Unit
				Min.	Typ.	Max.	
Forward voltage	V_F	I_F = 45 A, V_{GE} = 0 V	T_{vj} = 25 °C		1.38	1.58	V
			T_{vj} = 125 °C		1.52		
			T_{vj} = 150 °C		1.60		
Peak reverse recovery current	I_{RM}	V_{CC} = 500 V, I_F = 45 A, V_{GE}=-15 V, -di$_F$/dt = 4000 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		46.2		A
			T_{vj} = 125 °C		46.2		
			T_{vj} = 150 °C		46.2		
Recovered charge	Q_r	V_{CC} = 500 V, I_F = 45 A, V_{GE}=-15 V, -di$_F$/dt = 4000 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		1.27		µC
			T_{vj} = 125 °C		1.27		
			T_{vj} = 150 °C		1.27		
Reverse recovery energy	E_{rec}	V_{CC} = 500 V, I_F = 45 A, V_{GE}=-15 V, -di$_F$/dt = 4000 A/µs (T_{vj} = 150 °C)	T_{vj} = 25 °C		0.128		mJ
			T_{vj} = 125 °C		0.128		
			T_{vj} = 150 °C		0.128		
Thermal resistance, junction to heat sink	R_{thJH}	per diode, λ_{grease} = 3.3 W/(m·K)			0.689		K/W
Temperature under switching conditions	$T_{vj\,op}$			-40		150	°C

5 NTC-Thermistor

Table 9 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	T_{NTC} = 25 °C		5		kΩ
Deviation of R_{100}	$\Delta R/R$	T_{NTC} = 100 °C, R_{100} = 493 Ω	-5		5	%
Power dissipation	P_{25}	T_{NTC} = 25 °C			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2-1/(298{,}15\ K))]$		3375		K

(table continues...)

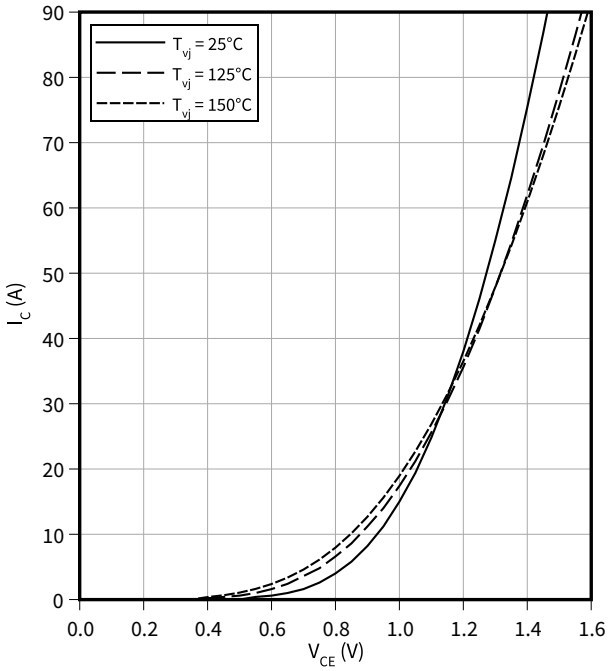
Table 9 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2\text{-}1/(298{,}15\ K))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2\text{-}1/(298{,}15\ K))]$		3433		K

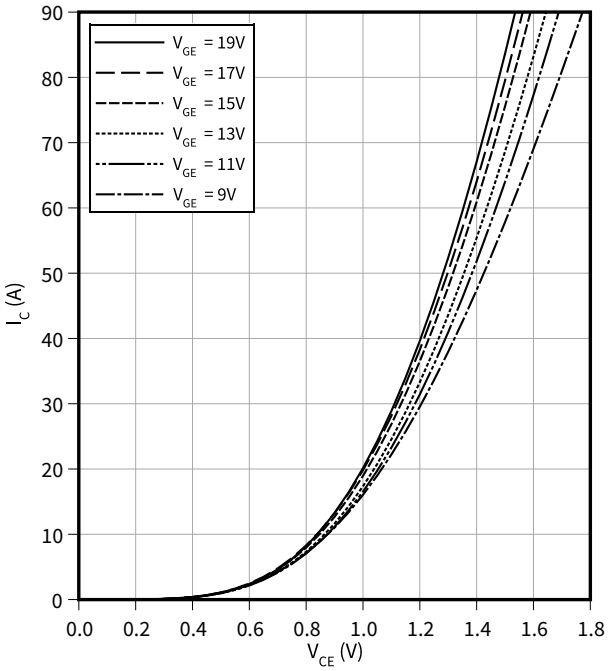
Note: Specification according to the valid application note.

6 Characteristics diagrams

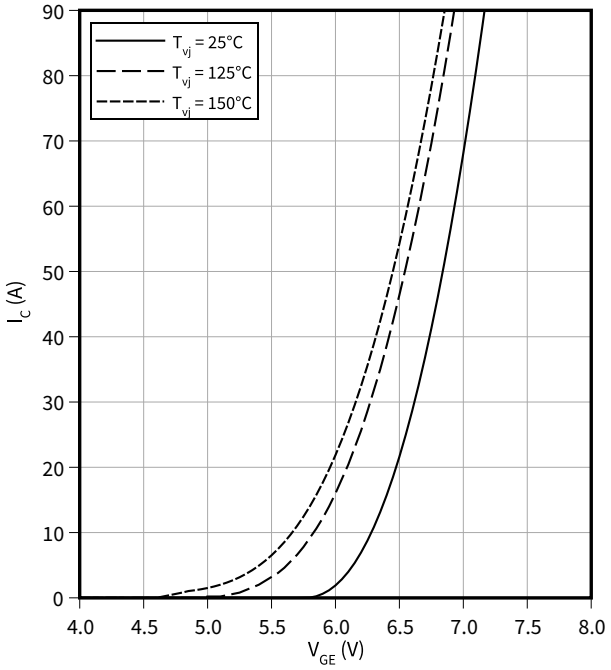
Output characteristic (typical), IGBT, Boost
$I_C = f(V_{CE})$
V_{GE} = 15 V



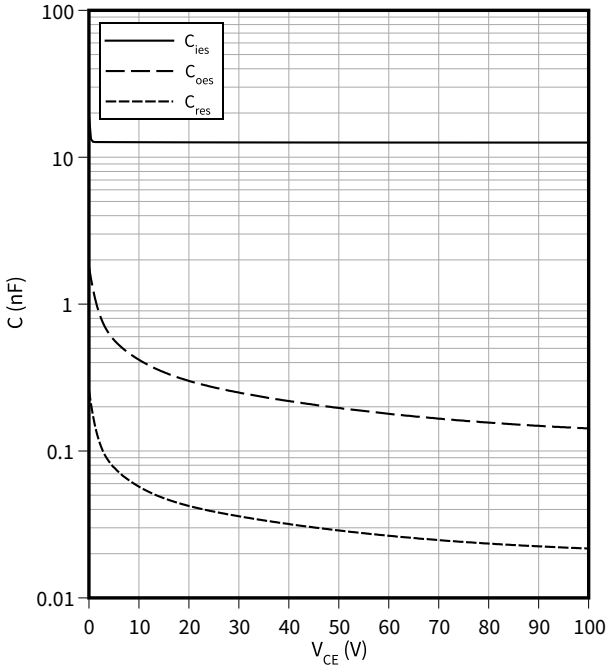
Output characteristic field (typical), IGBT, Boost
$I_C = f(V_{CE})$
T_{vj} = 150 °C



Transfer characteristic (typical), IGBT, Boost
$I_C = f(V_{GE})$
V_{CE} = 20 V



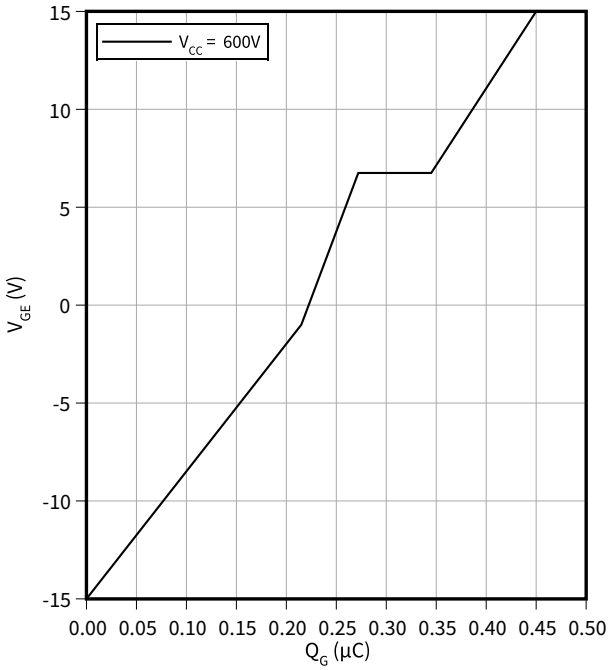
Capacity characteristic (typical), IGBT, Boost
$C = f(V_{CE})$
f = 100 kHz, V_{GE} = 0 V, T_{vj} = 25 °C



Gate charge characteristic (typical), IGBT, Boost

$V_{GE} = f(Q_G)$

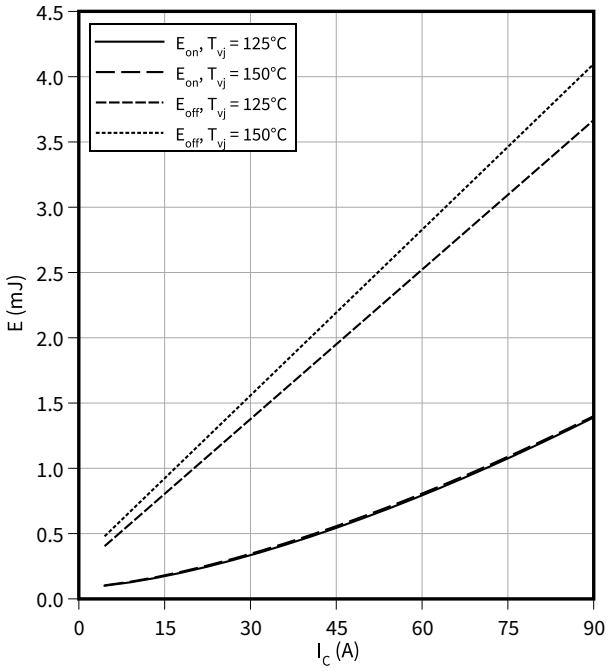
$I_C = 200\ A$, $T_{vj} = 25\ °C$



Switching losses (typical), IGBT, Boost

$E = f(I_C)$

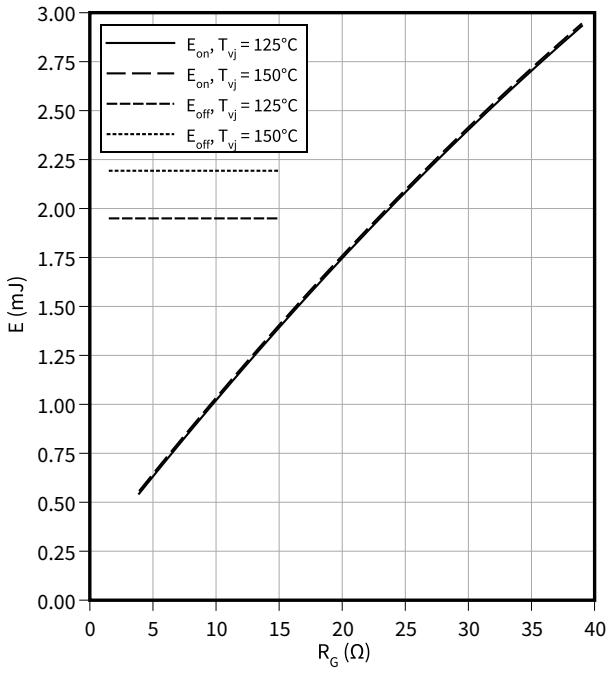
$R_{Goff} = 1.5\ \Omega$, $R_{Gon} = 3.9\ \Omega$, $V_{CC} = 500\ V$, $V_{GE} = \pm 15\ V$



Switching losses (typical), IGBT, Boost

$E = f(R_G)$

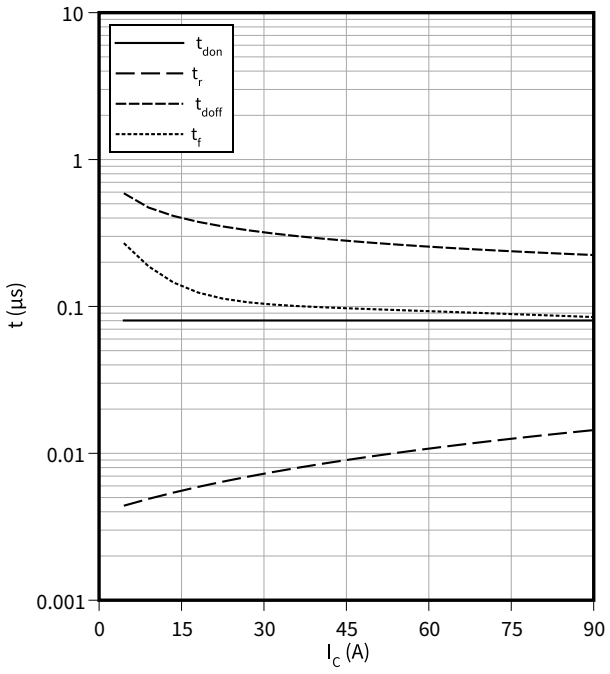
$I_C = 45\ A$, $V_{CC} = 500\ V$, $V_{GE} = \pm 15\ V$



Switching times (typical), IGBT, Boost

$t = f(I_C)$

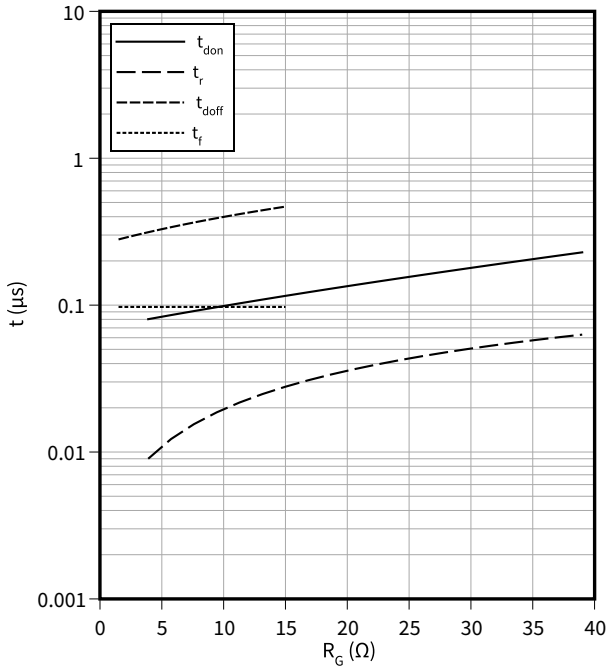
$R_{Goff} = 1.5\ \Omega$, $R_{Gon} = 3.9\ \Omega$, $V_{CC} = 500\ V$, $V_{GE} = \pm 15\ V$, $T_{vj} = 150\ °C$



Switching times (typical), IGBT, Boost

$t = f(R_G)$

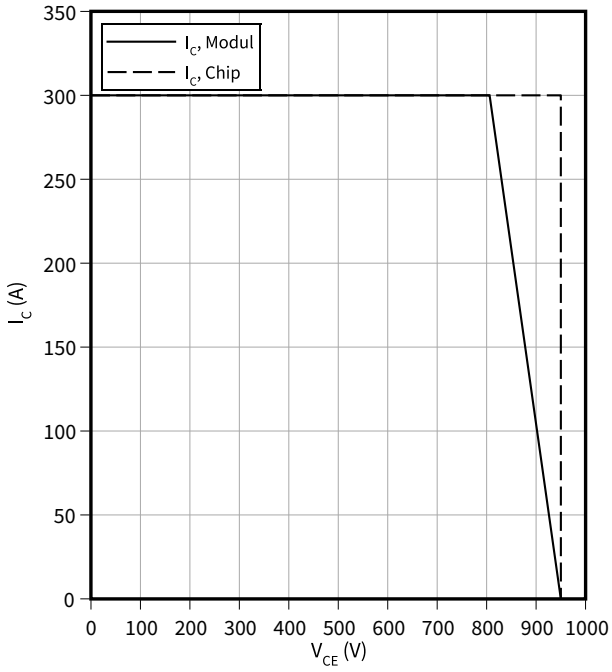
I_C = 45 A, V_{CC} = 500 V, V_{GE} = ± 15 V, T_{vj} = 150 °C



Reverse bias safe operating area (RBSOA), IGBT, Boost

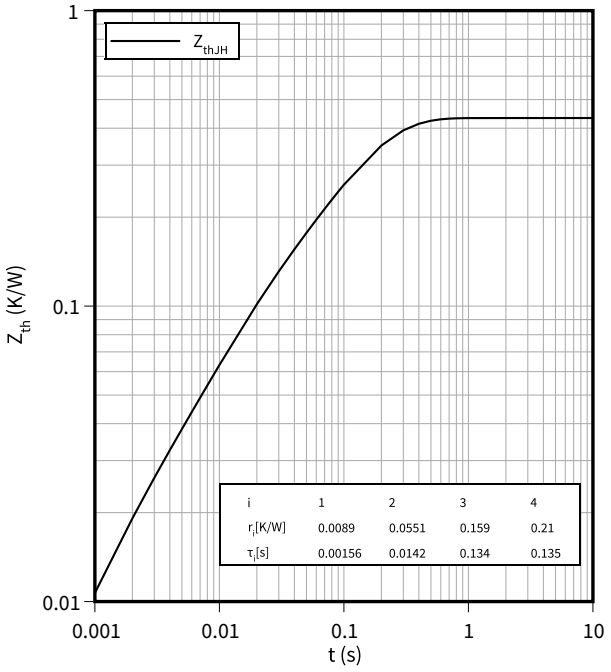
$I_C = f(V_{CE})$

R_{Goff} = 1.5 Ω, V_{GE} = ±15 V, T_{vj} = 150 °C



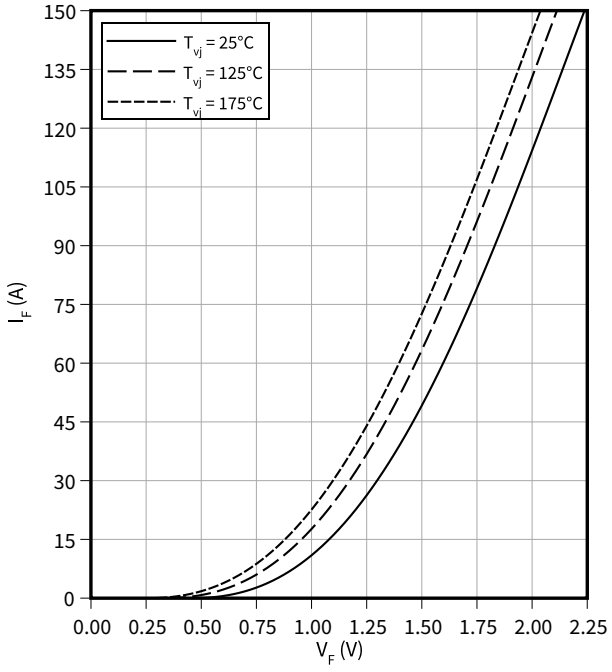
Transient thermal impedance , IGBT, Boost

$Z_{th} = f(t)$



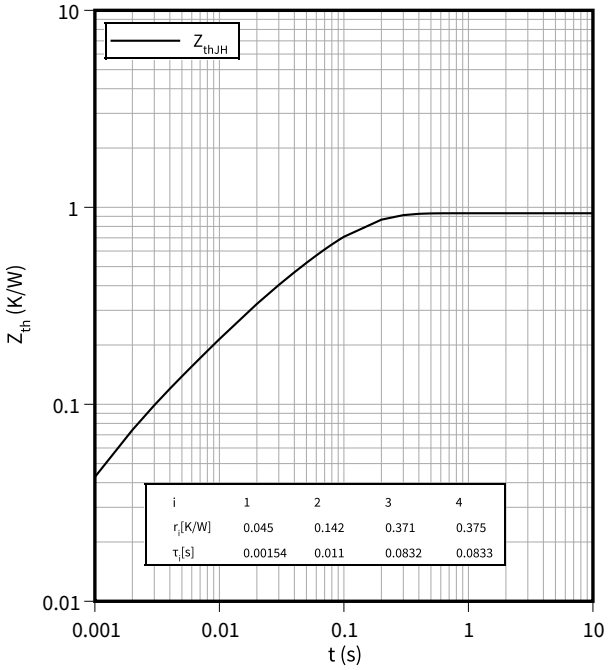
Forward characteristic (typical), Diode, Reverse

$I_F = f(V_F)$



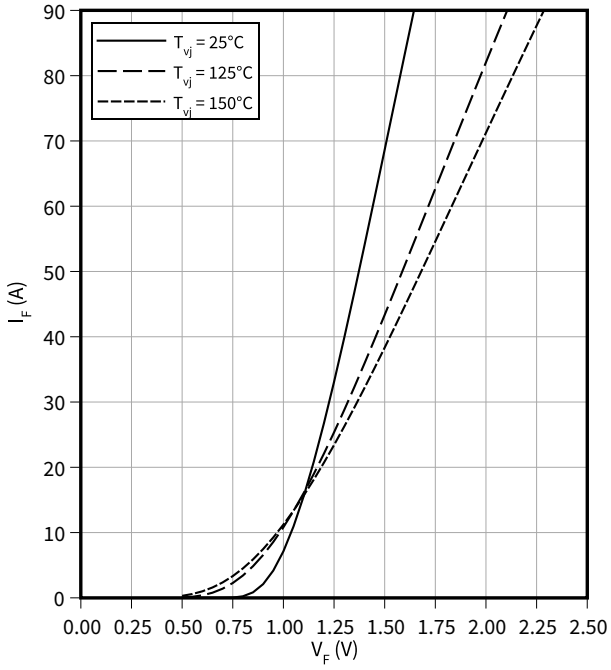
Transient thermal impedance, Diode, Reverse

$Z_{th} = f(t)$



Forward characteristic (typical), Diode, Boost

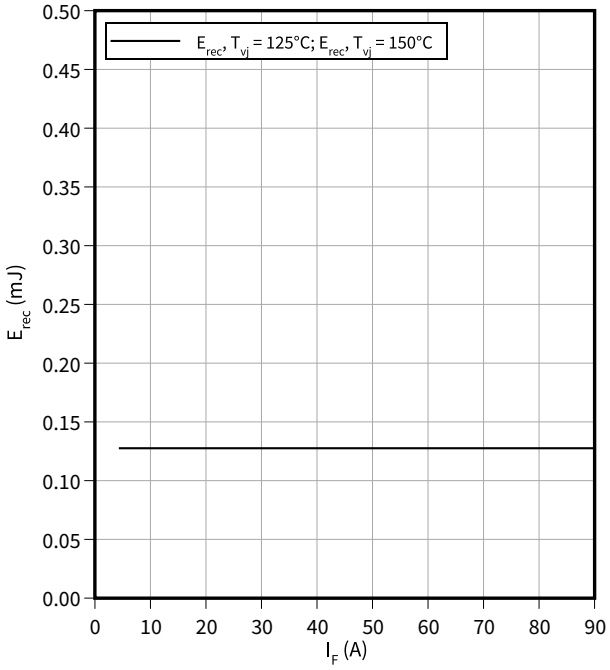
$I_F = f(V_F)$



Switching losses (typical), Diode, Boost

$E_{rec} = f(I_F)$

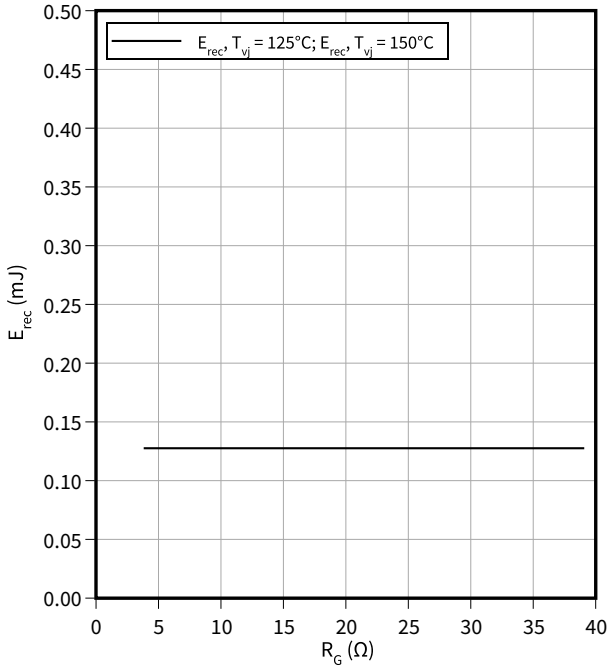
$R_{Gon} = 3.9\ \Omega$, $V_{CC} = 500\ V$



Switching losses (typical), Diode, Boost

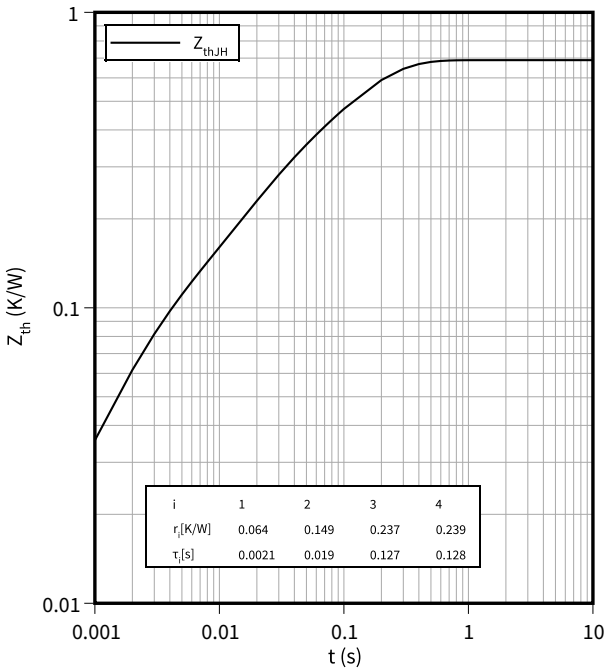
$E_{rec} = f(R_G)$

$I_F = 45\ A$, $V_{CC} = 500\ V$



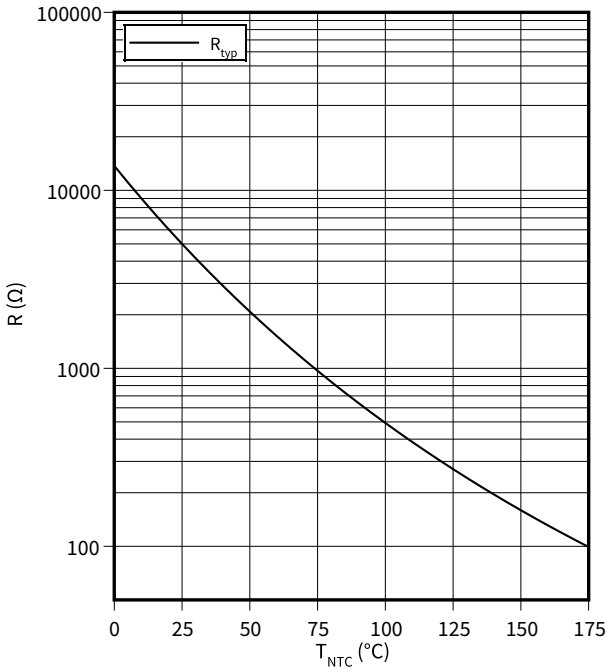
Transient thermal impedance, Diode, Boost

$Z_{th} = f(t)$



Temperature characteristic (typical), NTC-Thermistor

$R = f(T_{NTC})$



7 Circuit diagram

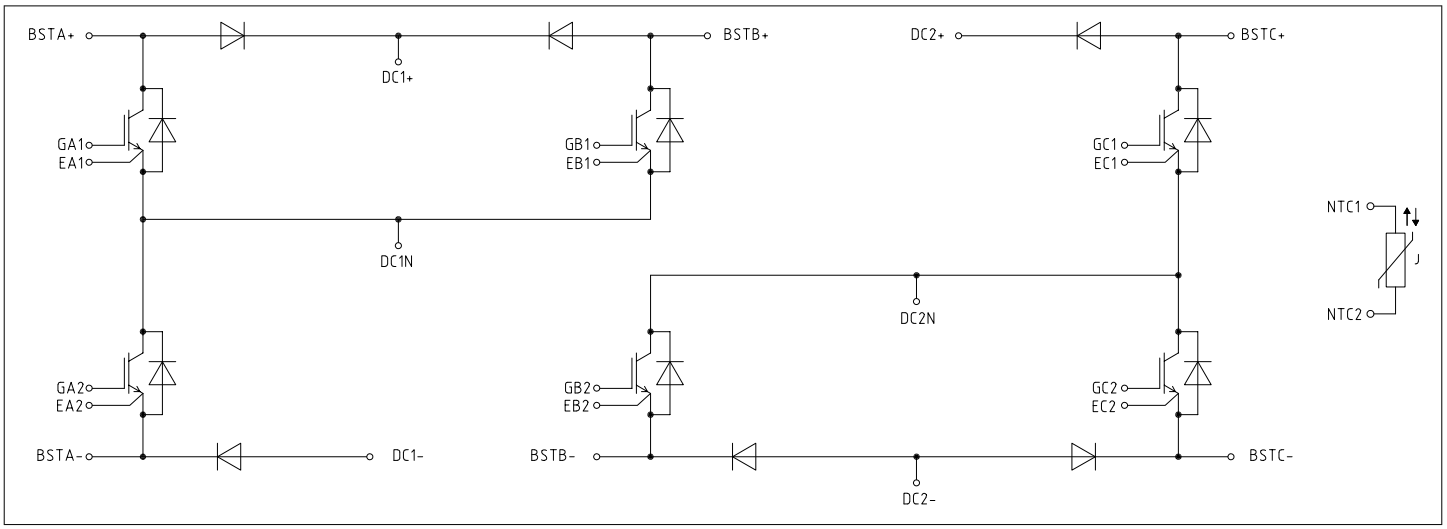


Figure 1

8 Package outlines

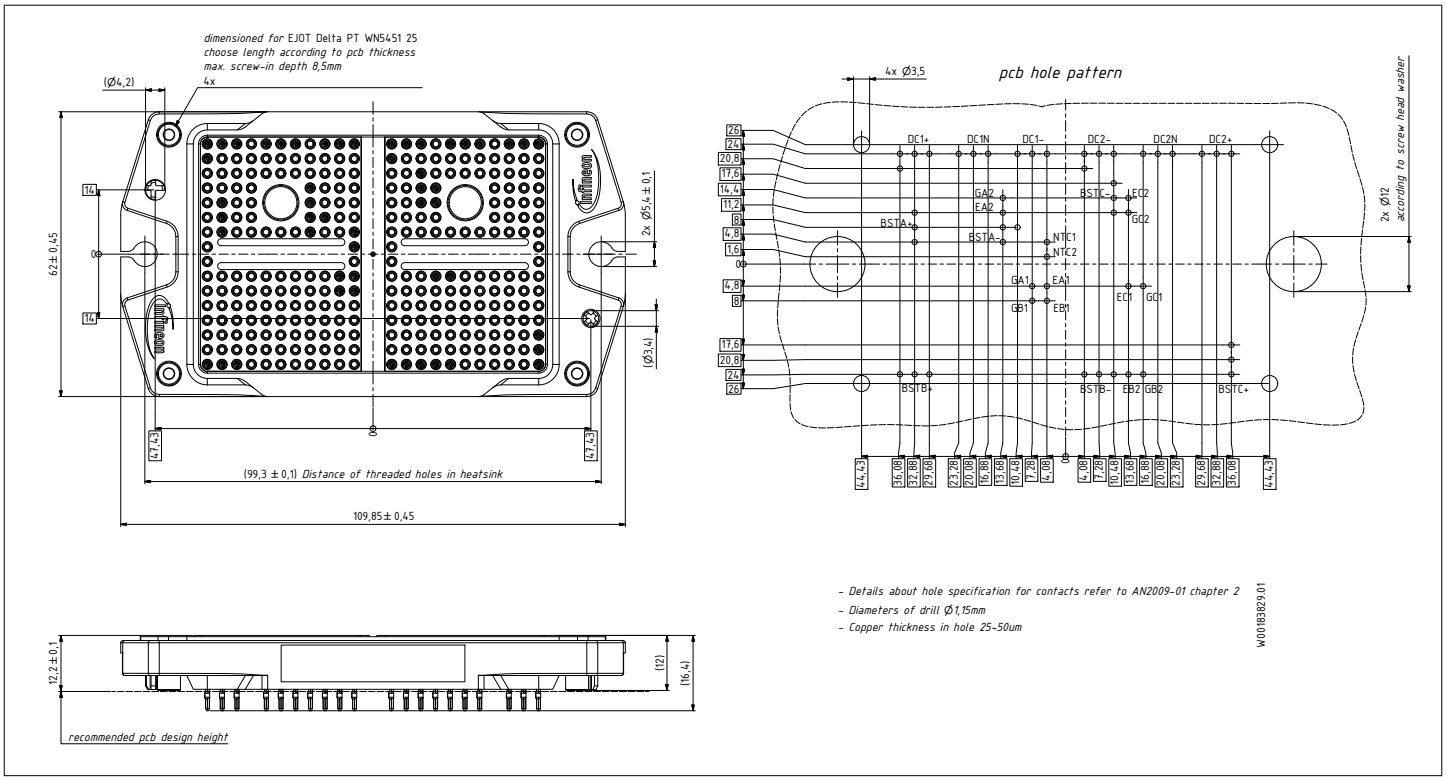


Figure 2

9 Module label code

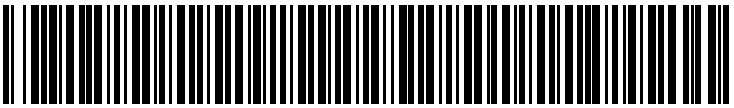
Module label code			
Code format	Data Matrix		Barcode Code128
Encoding	ASCII text		Code Set A
Symbol size	16x16		23 digits
Standard	IEC24720 and IEC16022		IEC8859-1
Code content	*Content* Module serial number Module material number Production order number Date code (production year) Date code (production week)	*Digit* 1 – 5 6 - 11 12 - 19 20 – 21 22 – 23	*Example* 71549 142846 55054991 15 30
Example	 7154914284655054991530	 7154914284655054991530	

Figure 3

Revision history

Document revision	Date of release	Description of changes
0.10	2022-04-29	Initial version
1.00	2022-08-24	Final datasheet

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Edition 2022-08-24

Published by

Infineon Technologies AG

81726 Munich, Germany

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Document reference
IFX-ABD624-002

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